



Introducing HyperLynx Signal Integrity/Power Integrity/Thermal

Major Product Benefits

HyperLynx Signal Integrity

- Identify possible signal integrity issues early in the design process
- Analyze design tradeoffs to fix signal integrity issues
- Perform full-board verification of routed boards in BoardSim
- Perform comprehensive what-if analysis in LineSim
- Integrated 3D field solver, S-parameter support, FasteEye/IBIS-AMI simulation, and Accurate BER prediction for SERDES busses
- Batch simulation wizard with on-chip timing for comprehensive DDRx bus analysis

HyperLynx Power Integrity

- Identify possible power integrity issues early in the design process
- Analyze design tradeoffs to fix power integrity issues
- Analyze DC Drop, Decoupling, and Noise issues in both BoardSim and LineSim
- Pinpoint areas of high current density and predict temperature rise with PI/Thermal co-simulation

HyperLynx Thermal

- Identify possible thermal issues early in the design process
- Analyze design tradeoffs to fix thermal issues
- Easy-to-use environment makes setting up and running thermal analysis simple
- Runs quickly and accurately due to self-adaptive locally refined meshes

HyperLynx Signal Integrity, Power Integrity, Thermal Enhancement Value

HyperLynx Support

When you buy products like HyperLynx SI/PI/Thermal that improve your design productivity and integrate tightly into your business, a comprehensive support program should be seen as an integral part of your product purchase.

Support is the insurance that allows your employees to concentrate on their work, while our support staff helps keep your downtime to a minimum and moves your project forward faster.

Key Support Benefits

- Software enhancements to bring you the latest improvements in product functionality, usability, and performance
- [SupportNet](https://supportnet.mentor.com) for rapid, secure access to online support
- Technical support backed by an award-winning support organization

Global Support and Services

supportnet.mentor.com | support_team@mentor.com

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What's New In HyperLynx 9.4 (August 2016)

HyperLynx v9.4 is a major release that adds many new features to HyperLynx's signal integrity, SERDES (including 3D electromagnetic), power-integrity, and mixed SI/PI simulation capabilities. The release also offers compatibility with Mentor's latest PCB-design tools and improved integration with the Xpedition® VX.2 PCB flow. Finally, HyperLynx v9.4 includes a large number of defect fixes and improvements.

New Signal Integrity Support for Rigid-Flex Designs

HyperLynx now supports multiple stackups in different areas of the board. This feature is available with the DDRx or GHZ license bundles or with the new Multiple Stackup license. The feature includes:

- Multiple Stackups Mode
- A new Stackup Manager
- Define unique Stackup Areas as rectangles or complex polygons
- Integration with Xpedition Specific to Rigid-Flex designs

New Signal Integrity Features

- Component Model Symbol added to LineSim to group drivers and receivers within a single component.
- IPC-2581 File Import added to BoardSim
- HTML-formatted reports added to Generic Batch.
- ODT Sweeps in DDRx Wizard in LineSim

New SerDes and 3D-Electromagnetic Features

- Automated Support for Series Passive Components in 3D Areas

New Power Integrity Features

- New Reports for DC Drop
- Advanced Decoupling Analysis Down to 10 KHz
- Loop Inductance Report from Advanced Decoupling Wizard
- New Decoupling Capacitor Model Libraries
- DC Drop Simulator Performance Improvement

GUI Improvements

- Improved Panning Capability and a New Measure Feature in BoardSim

IDEAS Implemented

- [14197](#) - Visual exposition of Batch Simulation Results stored in Excel Files
- [13122](#) - New LineSim IC symbol for SSO or SI/PI Co-simulation
- [13559](#) - Ability to import a HyperLynx stackup into CES

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About Mentor Customer Support

Mentor Graphics offers leading support for EDA tools, providing expert response to technical issues for the complete suite of Mentor Graphics products. We offer a smooth transition to product enhancements and new releases, access to technical assistance, an ever-expanding array of online solutions and optional services for special situations.

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